

# LN1371GTR

## Surface Mounting Chip LED

S-GW Type

### Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	60	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-25 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-30 to +100	$^\circ\text{C}$

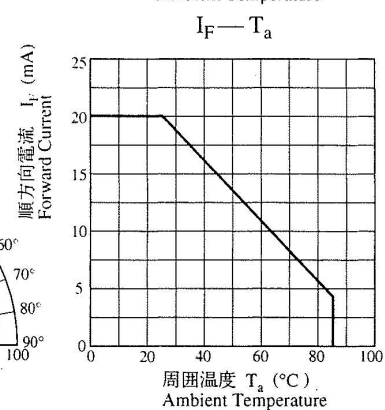
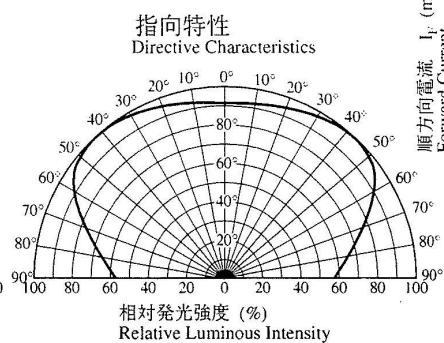
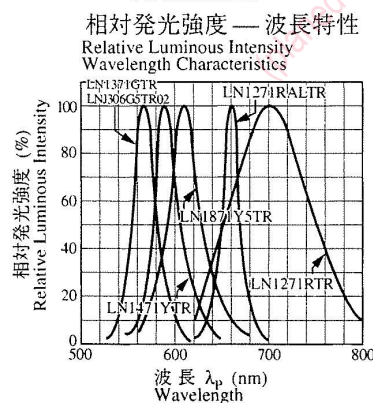
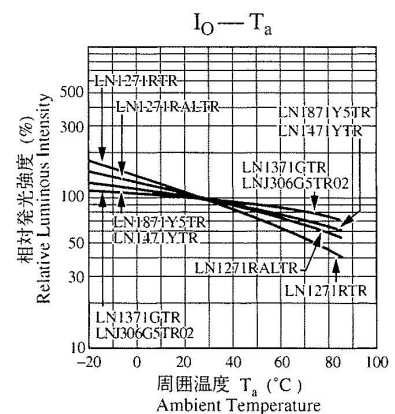
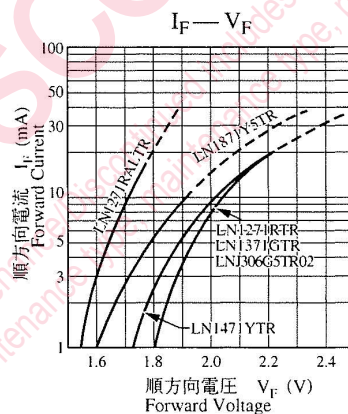
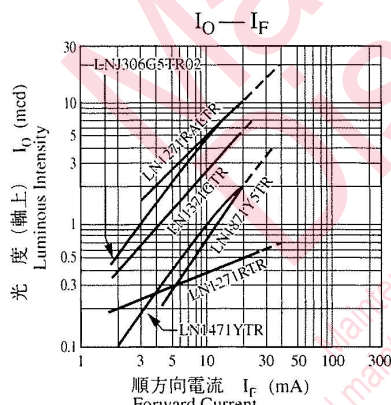
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### Lighting Color / Lens Color

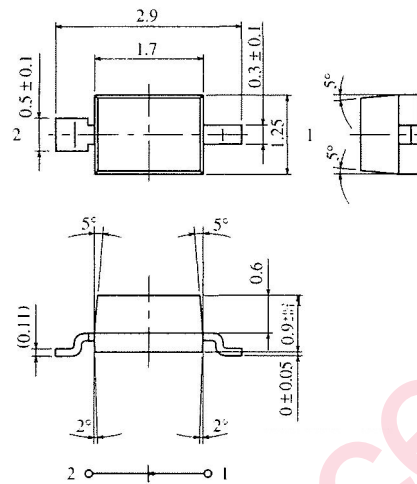
- Green / Green Diffused

### Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	$I_O$		0.9	2.6		mcd
Forward current	$I_F$			10		mA
Forward voltage	$V_F$	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_p$	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	$I_R$	$V_R = 4\text{ V}$			10	$\mu\text{A}$



## ■ Package (Unit: mm)



- Pin name
- 1: Anode
- 2: Cathode

**Maintenance/Discontinued**

Maintenance/Discontinued includes following four Product lifecycle stage.  
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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